Lattice Semiconductor Corporation - <u>LFEC10E-5Q208C Datasheet</u>



Welcome to **E-XFL.COM**

Understanding <u>Embedded - FPGAs (Field Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	10200
Total RAM Bits	282624
Number of I/O	147
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	208-BFQFP
Supplier Device Package	208-PQFP (28x28)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfec10e-5q208c

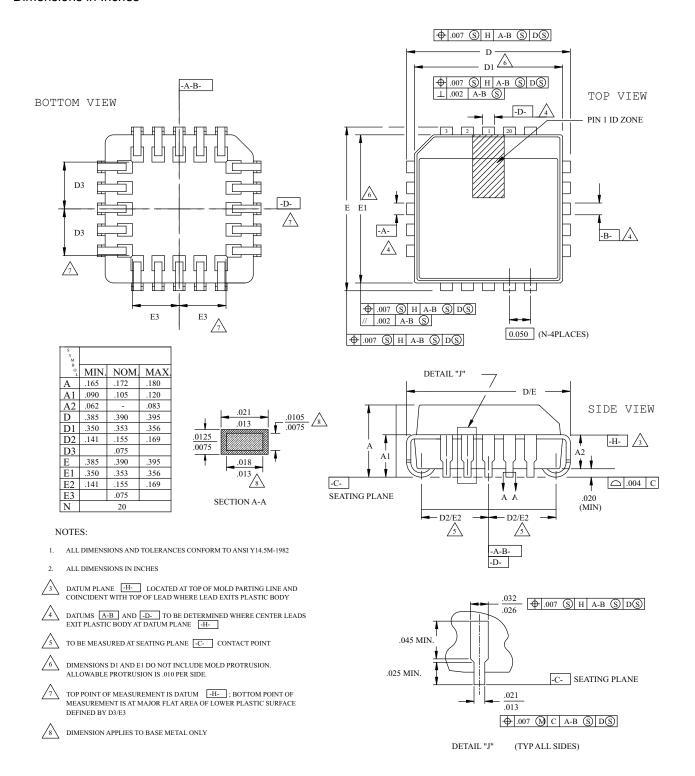
Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



20-Pin PLCC Package

Dimensions in Inches

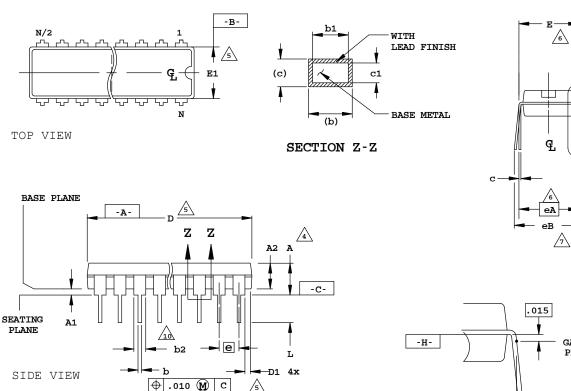


SEE DETAIL



20-Pin Plastic DIP Package

Dimensions in Inches



NOTES:

- 1. CONTROLLING DIMENSION: INCH.
- 2. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M
- 3. DISTANCE BETWEEN LEADS INCLUDING DAMBAR
- PROTRUSIONS TO BE .005 MINIMUM. DIMENSIONS A, A1 & L ARE MEASURED WITH THE PACKAGE SEATED IN JEDEC SEATING
- PLANE GAUGE GS-3.
- PLANE GAGE GS-3.

 DIMENSIONS D, D1 AND E1
 DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS.

 MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED .010

 6 E AND eA MEASURED WITH THE LEADS CONSTRAINED

 TO BE PERPENDICULAR TO DATUM C-
- 70 BE PERPENDICULAR TO DATOM.

 eB AND eC ARE MEASURED AT THE LEAD TIPS

 with the Leads unconstrained. 8 N IS THE MAXIMUM NUMBER OF LEAD
- POSITIONS.

 9. POINTED OR ROUNDED LEAD TIPS ARE PREFERRED TO EASE INSERTION
- 10 b2 MAXIMUM DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSIONS. DAMBAR PROTRUSIONS SHALL NOT EXCEED .010
- 11 DATUM PLANE -H- COINCIDENT WITH THE BOTTOM OF LEAD , WHERE LEAD EXITS BODY

-Н-	GAGE
	—— ec

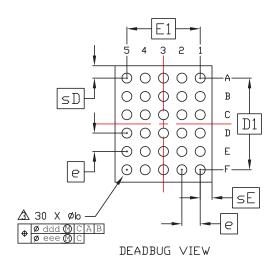
DETAIL A

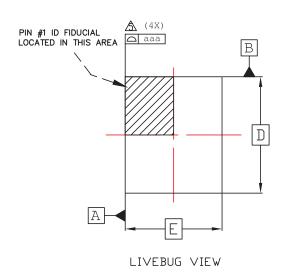
]			
S Y M B	I	NCHES		N O T
O L	MIN.	NOM.	MAX.	T E
Α	-	ı	.210	4
A 1	.015	-	-	4
A 2	.115	.130	.195	
b	.014	.018	.022	
b1	.014	.018	.020	
b2	.045	.060	.070	10
С	.008	.010	.014	
C1	.008	.010	.011	
D	.980	1.030	1.060	5
D1	.005			5
E	.300	.310	. 325	6
E1	.240	.250	.280	5
е	.100 BSC			
eА	.300 BSC			6
eВ	430		7	
еC	.000	-	.060	7
L	.115	.130	.150	4

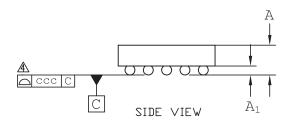


30-Ball WLSC Package

Dimensions in Millimeters







Notes:

- 1 ALL DIMENSIONS AND TOLERANCE PER ASME Y 14.5M 1994. 2 ALL DIMENSIONS ARE IN MILLIMETERS.
- △ DIMENSION "6" IS MEASURED AT THE MAXIMUM BUMP DIAMETER PARALLEL TO PRIMARY DATUM C.
- A PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BUMPS.

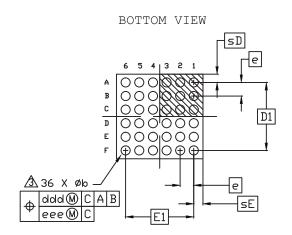
 A BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE
- PACKAGE BODY.

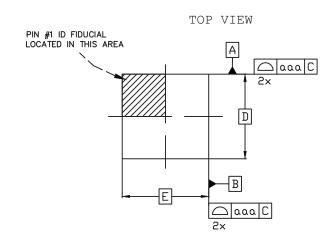
REF.	Min.	Nom.	Max.
Α	_	ı	0.600
A1	0.140	ı	-
b	0.230	0.260	0.290
D	2.5	537 BSC)
Е	2	.114 BSC	,
D1	i	2.00 BSC)
E1	1.60 BSC		
е	0.40 BSC		
sD	_	0.26	_
sE	_	0.27	_
۵۵۵	0.030		
CCC	0.050		
ddd	0.015		
666		0.050	

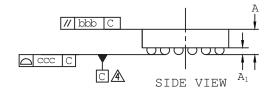


36-Ball WLCS Package Option 2: MachXO3[™]

Dimensions in Millimeters







NOTES:

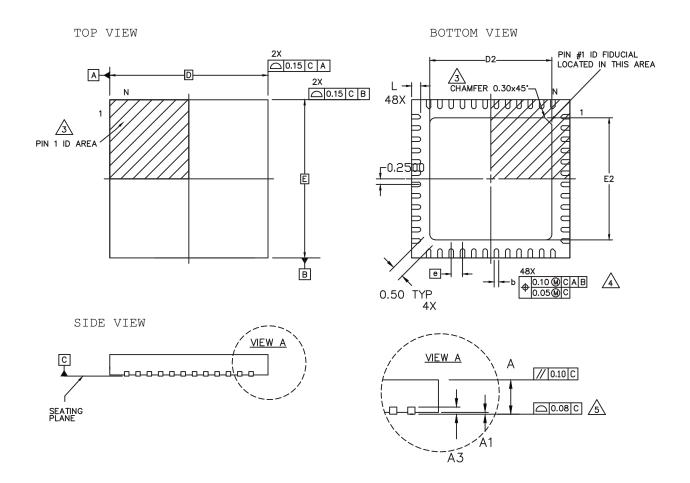
- 1. ALL DIMENSIONS AND TOLERANCE PER ASME Y 14.5M 1994.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.
- △ DIMENSION "b" IS MEASURES AT THE MAXIMUM BUMP DIAMETER PARALLEL TO PRIMARY DATUM [C].
- \triangle PRIMARY DATUM $\boxed{\text{C}}$ AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BUMPS.

REF.	Min.	Nom.	Max.
A	0.510	0.543	0.576
A1	0.167	0.196	0.225
b	0.239	0.266	0.319
D	2	2.487 BS	C
E		2.541 BS	C
D1		2.00 BSC	;
E1	2.00 BSC		
е	(0.40 BSC	!
sD	-	0.244	1
sE	- 0.271 -		-
aaa	0.025		
bbb	0.060		
ccc	0.030		
ddd	0.0150		
eee		0.050	



48-Pin QFN Package Option 2: L-ASC10, iCE40 Ultra, iCE40 UltraPlus, MachXO2

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.

2. ALL DIMENSIONS ARE IN MILLIMETERS.

<u>3</u>

EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

4

DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM TERMINAL TIP.

/5\

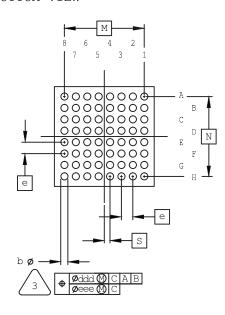
APPLIES TO EXPOSED PORTION OF TERMINALS.

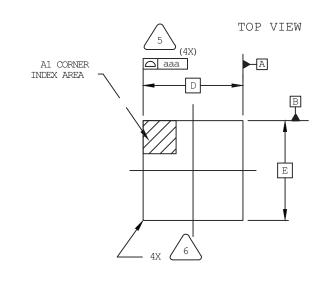
SYMBOL	MIN.	NOM.	MAX.
А	0.80	0.90	1.00
A1	0.00	0.02	0.05
A3	0.2 REF		
D		7.0 BSC	
D2	5.30	5.40	5.50
E	7.0 BSC		
E2	5.30	5.40	5.50
b	0.15	0.20	0.25
е	0.50 BSC		
L	0.35	0.40	0.45

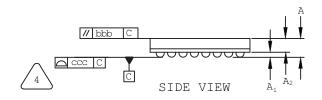


Dimensions in Millimeters

BOTTOM VIEW







NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C].



PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



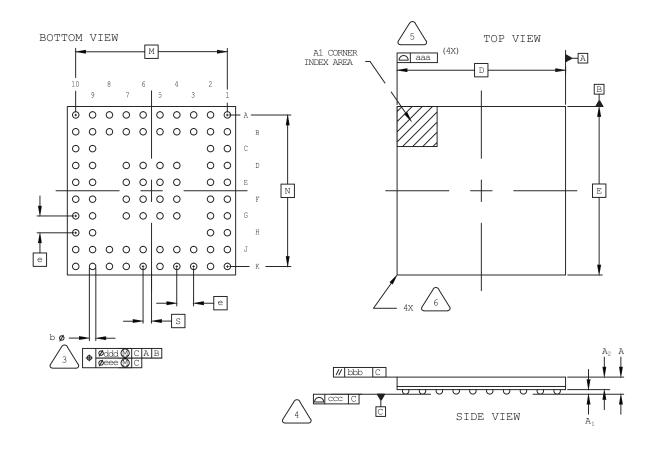
BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.



SYMBOL	MIN.	NOM.	MAX.
А	-	_	1.00
A1	0.11	_	-
A2	0.62	-	_
D/E		3.50 BSC	
M/N		2.80 BSC	
S		0.20 BSC	
b	0.20	0.25	0.30
е	0.40 BSC		
aaa	0.10		
bbb	0.10		
ccc	0.08		
ddd	0.15		
eee		0.08	



Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C].



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

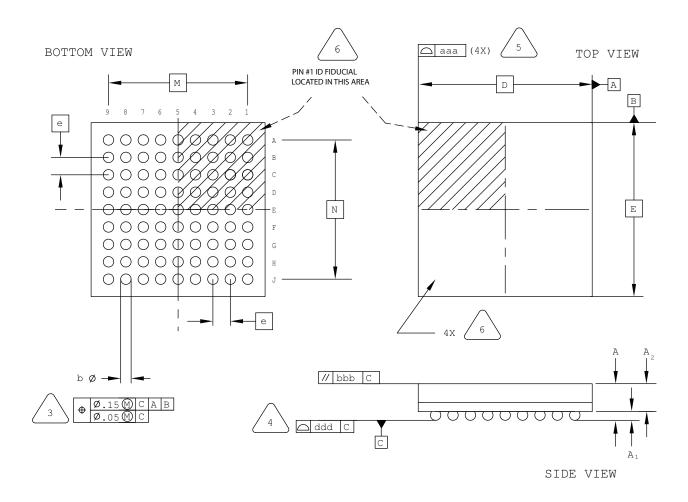


SYMBOL	MIN.	NOM.	MAX.
А	-	-	1.00
A1	0.11	-	-
A2	0.61	-	-
D/E		6.50 BSC	
M/N		5.85 BSC	
S	(.325 BSC	
b	0.20	0.25	0.30
е	0.65 BSC		
aaa	0.10		
bbb	0.10		
ccc	0.08		
ddd	0.15		
eee		0.05	



81-Ball csBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING
PLANE ARE DEFINED BY THE SPHERICAL
CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

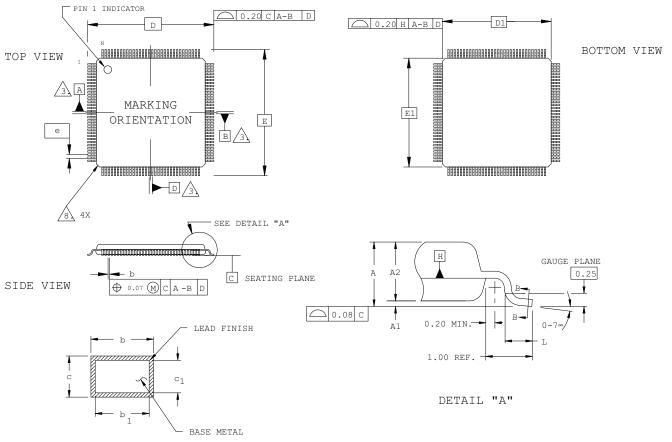


SYMBOL	MIN.	NOM.	MAX.
А	-	ı	1.00
A1	0.10	-	-
A2	-	-	0.90
D/E	5	.00 BSC	
M/N	4.00 BSC		
b	0.20	0.25	0.30
е	0.50 BSC		
aaa	-	_	0.10
bbb	-	_	0.10
ddd	_	_	0.10



128-Pin TQFP Package

Dimensions in Millimeters



SECTION B - B

NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5 1982.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.

 $\sqrt{3}$ DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.

- 4. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION.
 ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1
- 5. THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
- 6. SECTION B-B:
 THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE
 LEAD BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.
- 7. A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.

8 EXACT SHAPE OF EACH CORNER IS OPTIONAL.

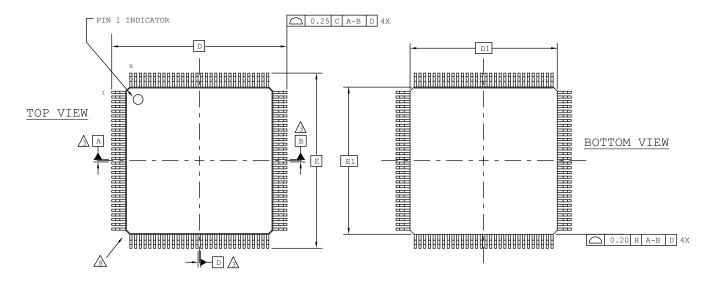
SIDE VIEW

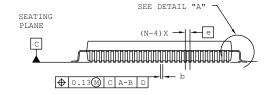
SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.60
A1	0.05	-	0.15
A2	1.35	1.40	1.45
D		16.00 BSC	
D1		14.00 BSC	
Е	16.00 BSC		
E1		14.00 BSC	
L	0.45	0.60	0.75
N		128	
е	0.40 BSC		
b	0.13 0.18 0.23		0.23
b1	0.13	0.16	0.19
С	0.09	0.15	0.20
c1	0.09	0.13	0.16

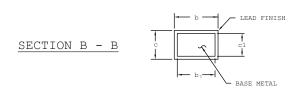


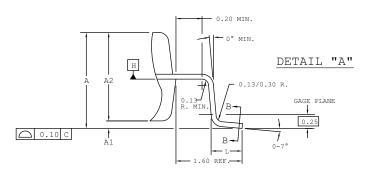
160-Pin PQFP Package

Dimensions in Millimeters









NOTES:

- 1.0 DIMENSIONING AND TOLERANCING PER ANSI Y14.5 1982.
- 2.0 ALL DIMENSIONS ARE IN MILLIMETERS.
- $\stackrel{\textstyle \wedge}{\Im}$ datums a, b and d to be determined at datum plane H.
- 4.0 DIMENSIONS D1 AND E1 D0 NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1 DIMENSIONS.
- 5.0 THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
- 6.0 SECTION B-B:
 THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE
 LEAD BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.
- 7.0 A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
- & EXACT SHAPE OF EACH CORNER IS OPTIONAL.

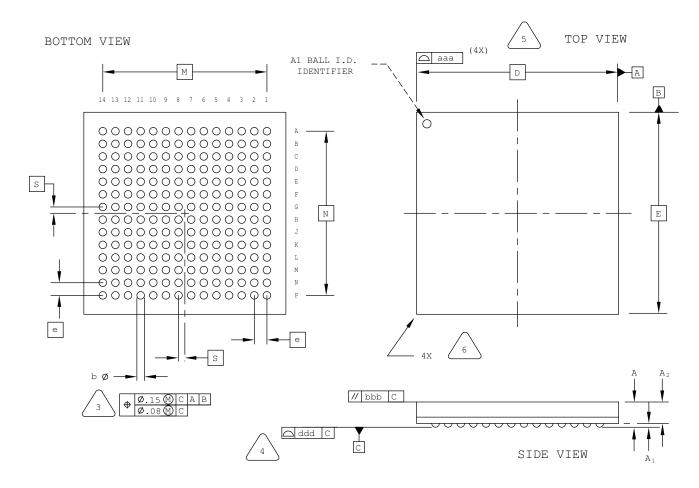
A EXACT SHAPE OF EXPOSED HEATSINK IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	=	-	4.10
A1	0.25	-	0.50
A2	3.20	3.40	3.60
D	31.20 BSC		!
D1		28.00 BSC	!
E		31.20 BSC	!
E1		28.00 BSC	!
L	0.73	0.88	1.03
N		160	
е		0.65 BSC	
b	0.22	-	0.40
b1	0.22	0.30	0.36
С	0.11	-	0.23
c1	0.11	0.15	0.19



196-Ball csBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



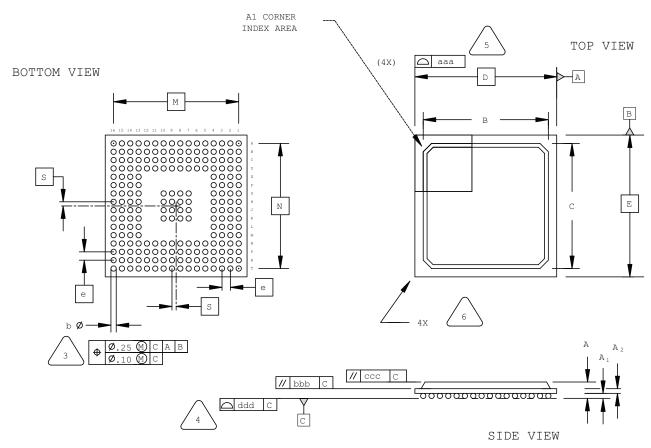
BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.



SYMBOL	MIN.	NOM.	MAX.
А	-	-	1.00
A1	0.15	_	_
A2	_	_	0.85
D/E	8	.00 BSC	
M/N	6.50 BSC		
S	0.25 BSC		
b	0.25	0.30	0.35
е	0.50 BSC		
aaa	_	_	0.10
bbb	_	_	0.10
ddd	_	_	0.08



Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

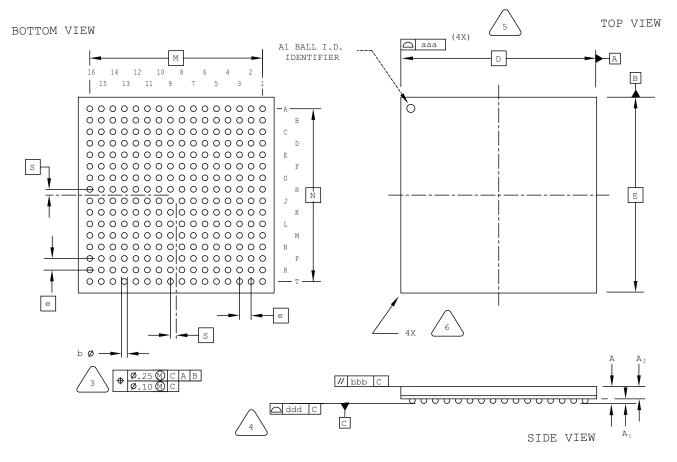


SYMBOL	MIN.	NOM.	MAX.
A	1.30	1.70	2.10
A1	0.30	0.50	0.70
A2	0.30	0.50	0.70
B/C	14.80	15.30	15.80
D/E	17.00 BSC		
M/N	15.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
е	1.00 BSC		
aaa	_	_	0.20
bbb	_	_	0.25
ccc	_	_	0.35
ddd	_	_	0.20



256-Ball ftBGA Package Option 3: MachXO2

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM $\boxed{\text{C}}$



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

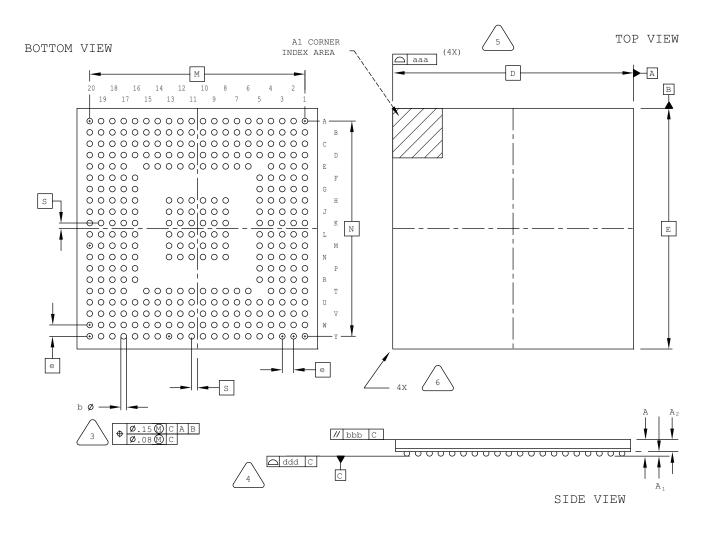


SYMBOL	MIN.	NOM.	MAX.
A	1.40	1.55	1.70
A1	0.30	_	-
A2	1.00	-	-
D/E	17.0 BSC		
M/N	15.0 BSC		
S	0.50 BSC		
b	0.40	0.50	0.60
е	1.0 BSC		
aaa	_	_	0.20
bbb	_	_	0.25
ddd	_	_	0.12



332-Ball caBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING
PLANE ARE DEFINED BY THE SPHERICAL
CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

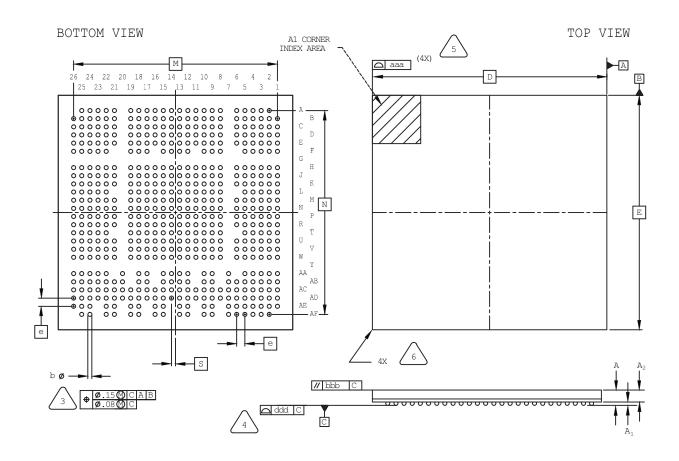


SYMBOL	MIN.	NOM.	MAX.
А	-	-	2.00
A1	0.25	_	_
A2	0.65	_	_
D/E	17.0 BSC		
M/N	15.2 BSC		
S	0.40 BSC		
b	0.40	0.45	0.50
е	0.80 BSC		
aaa	-	-	0.15
bbb	_	-	0.20
ddd	_	-	0.20



554-Ball caBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.

2. ALL DIMENSIONS ARE IN MILLIMETERS.

 $\sqrt{3}$

DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM $\boxed{\mathbb{C}}$



PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



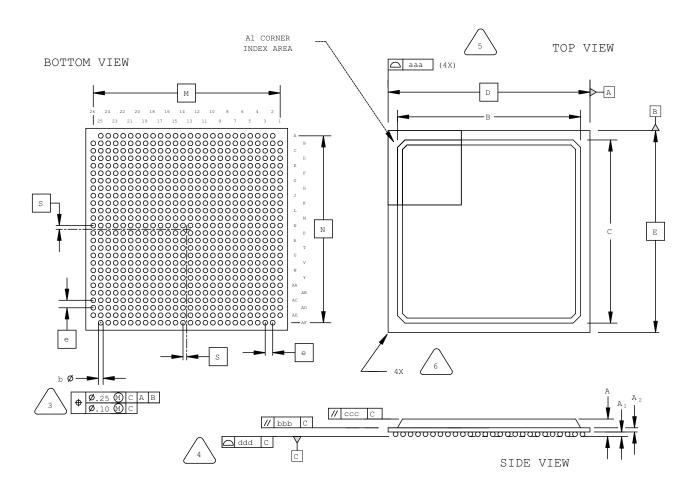
BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.



SYMBOL	MIN.	NOM.	MAX.
А	-	-	1.76
A1	0.25	0.30	0.35
A2	0.80	-	-
D/E	23.0 BSC		
M/N	20.0 BSC		
S	0.40 BSC		
b	0.35	0.40	0.45
е	0.80 BSC		
aaa	_	_	0.15
bbb	_	_	0.20
ddd	_	_	0.12



Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



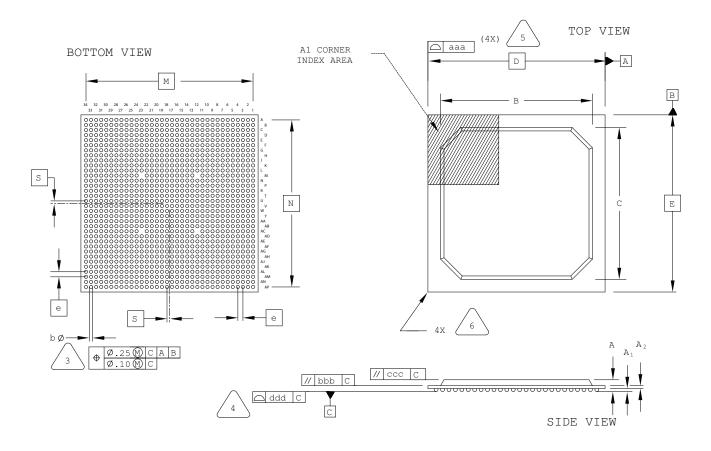
BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.



SYMBOL	MIN.	NOM.	MAX.
А	1.70	2.15	2.60
A1	0.30	0.50	0.70
A2	0.30	0.50	0.70
B/C	23.80	24.80	25.80
D/E	27.00 BSC		
M/N	25.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
е	1.00 BSC		
aaa	-	-	0.20
bbb	-	_	0.25
ccc	-	-	0.35
ddd	_	_	0.20



Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C]



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.



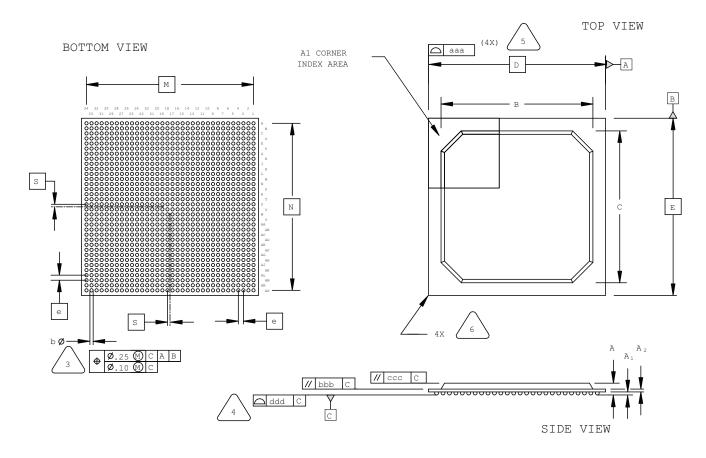
EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

Note: Depopulated ball locations are M12, M23, AC12, and AC23.

SYMBOL	MIN.	NOM.	MAX.
А	1.90	2.25	2.60
A1	0.30	0.50	0.70
A2	0.40	0.60	0.80
B/C	29.80	30.30	30.80
D/E	35.00 BSC		
M/N	33.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
е	1.00 BSC		
aaa	_	_	0.20
bbb	_	_	0.25
ccc	-	-	0.35
ddd	_	_	0.20



Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.

2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

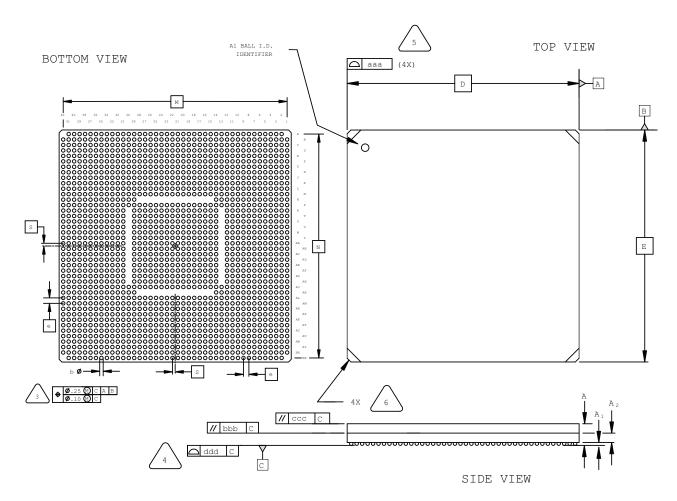


SYMBOL	MIN.	NOM.	MAX.
A	1.90	2.25	2.60
A1	0.30	0.50	0.70
A2	0.40	0.60	0.80
B/C	29.80	30.30	30.80
D/E	35.00 BSC		
M/N	33.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
е	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	-	-	0.20



1704-Ball Ceramic fcBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY. PACKAGE BODY INCLUDES SUBSTRATE AND LID.





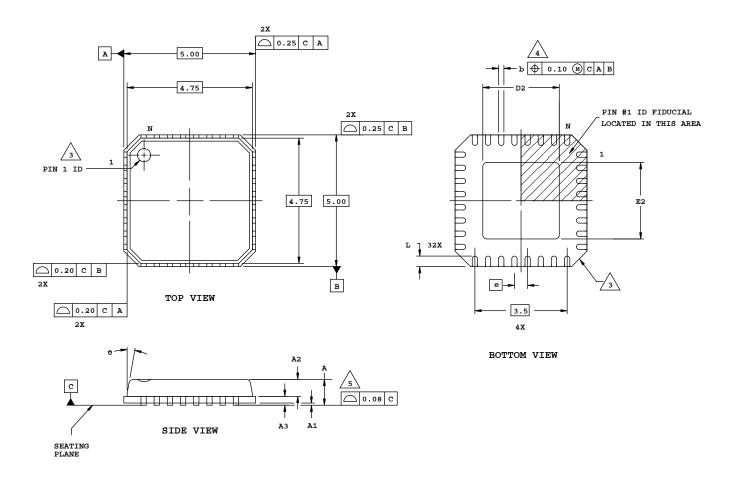
SYMBOL	MIN.	NOM.	MAX.
A	4.30	4.80	5.30
A1	0.30	0.50	0.70
A2	1.30	1.60	1.90
D/E	42.50 BSC		
M/N	41.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
е	1.00 BSC		
aaa			0.20
bbb			0.25
ccc	-	-	0.35
ddd	-	-	0.20



Appendix A. Package Archive

32-Pin QFN (Punch Singulated) Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.

<u>3</u> I

EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.



DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.20 AND 0.25 mm FROM TERMINAL TIP.



APPLIES TO EXPOSED PORTION OF TERMINALS.

SYMBOL	MIN.	NOM.	MAX.
A	-	0.85	1.00
A1	0.00	0.01	0.05
A2	0.00	0.65	1.00
A 3	0.20 REF		
D2	1.25	2.70	3.25
E2	1.25	2.70	3.25
е	0.50 BSC		
b	0.18	0.24	0.30
L	0.30	0.40	0.50
Ð	-	-	12